1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		30	V
$I_{F(RMS)}$	Forward rms current		7	A
$I_{F(AV)}$	Average forward current δ = 0.5, square wave	T_C = 135 °C	8	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal	75	A
P_{ARM}	Repetitive peak avalanche power	t_p = 10 µs, T_j = 125 °C	215	W
T_{stg}	Storage temperature range		-65 to +150	°C
T_j	Maximum operating junction temperature (1)		150	°C

Notes:

(1)$(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal parameters

Symbol	Parameter	Max. value	Unit
$R_{th(j-c)}$	Junction to case	2.5	°C/W

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$	-		1	mA
		T_j = 100 °C		-	15	40	
V_F (1)	Forward voltage drop	T_j = 25 °C	I_F = 8 A	-		0.49	V
		T_j = 125 °C		-	0.35	0.40	
		T_j = 25 °C	I_F = 16 A	-		0.63	
		T_j = 125 °C		-	0.448	0.57	

Notes:

(1)Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses, use the following equation:

$P = 0.23 \times I_{F(AV)} + 0.021 \times I_{F^2(RMS)}$

1.1 Characteristics (curves)

Figure 1: Average forward power dissipation versus average forward current

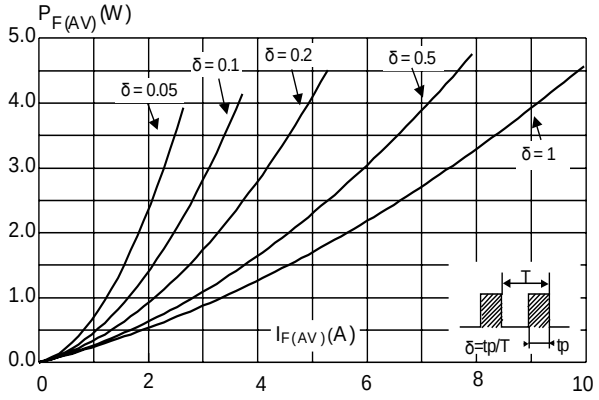


Figure 2: Average forward current versus ambient temperature (δ = 0.5)

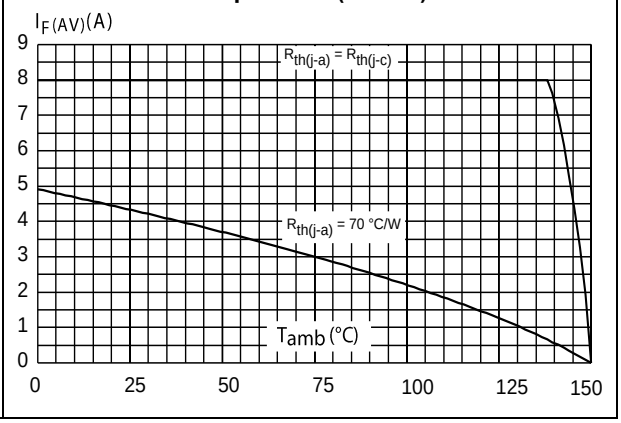


Figure 3: Normalized avalanche power derating versus pulse duration (T_j = 125 °C)

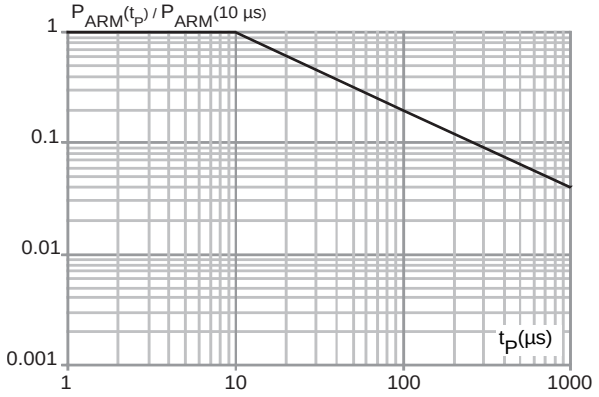


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

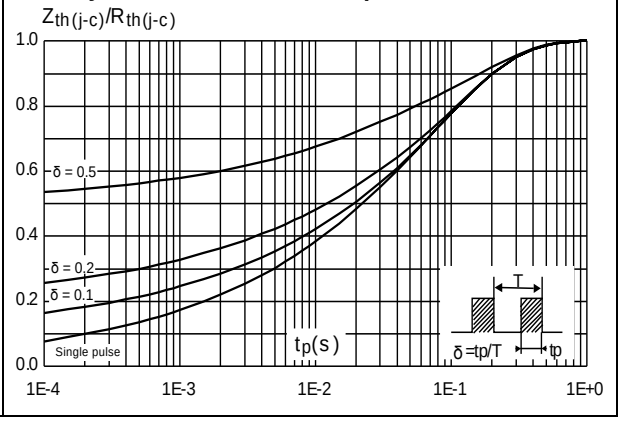


Figure 5: Reverse leakage current versus reverse voltage applied (typical values)

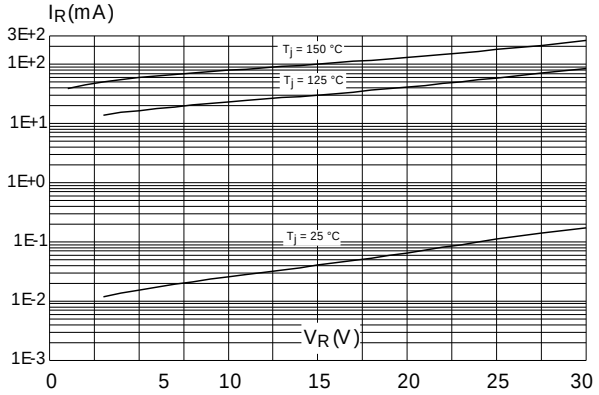


Figure 6: Junction capacitance versus reverse voltage applied (typical values)

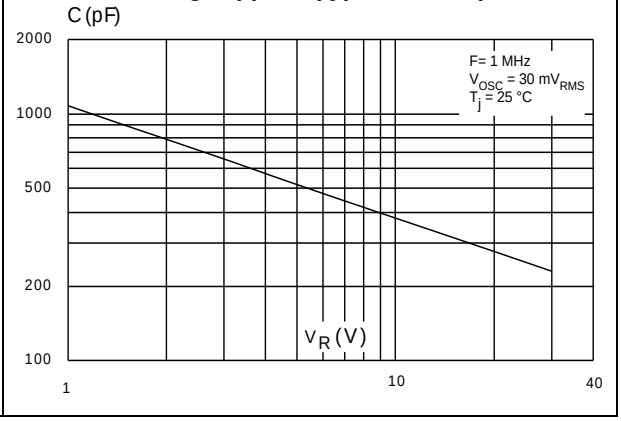


Figure 7: Forward voltage drop versus forward current

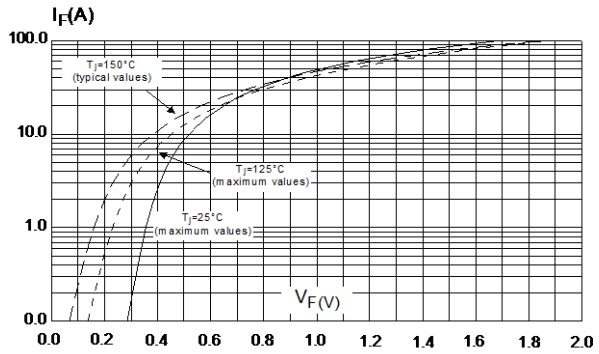
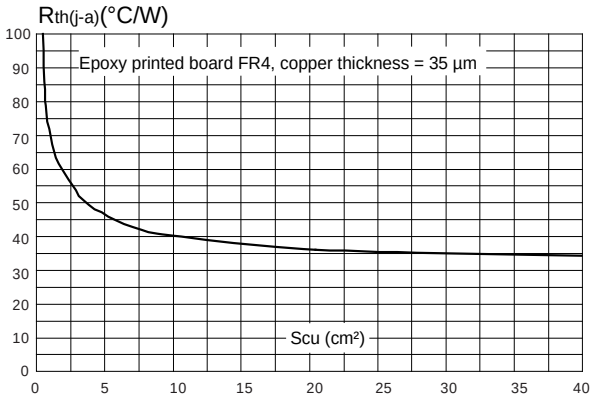


Figure 8: Thermal resistance junction to ambient versus copper surface under tab



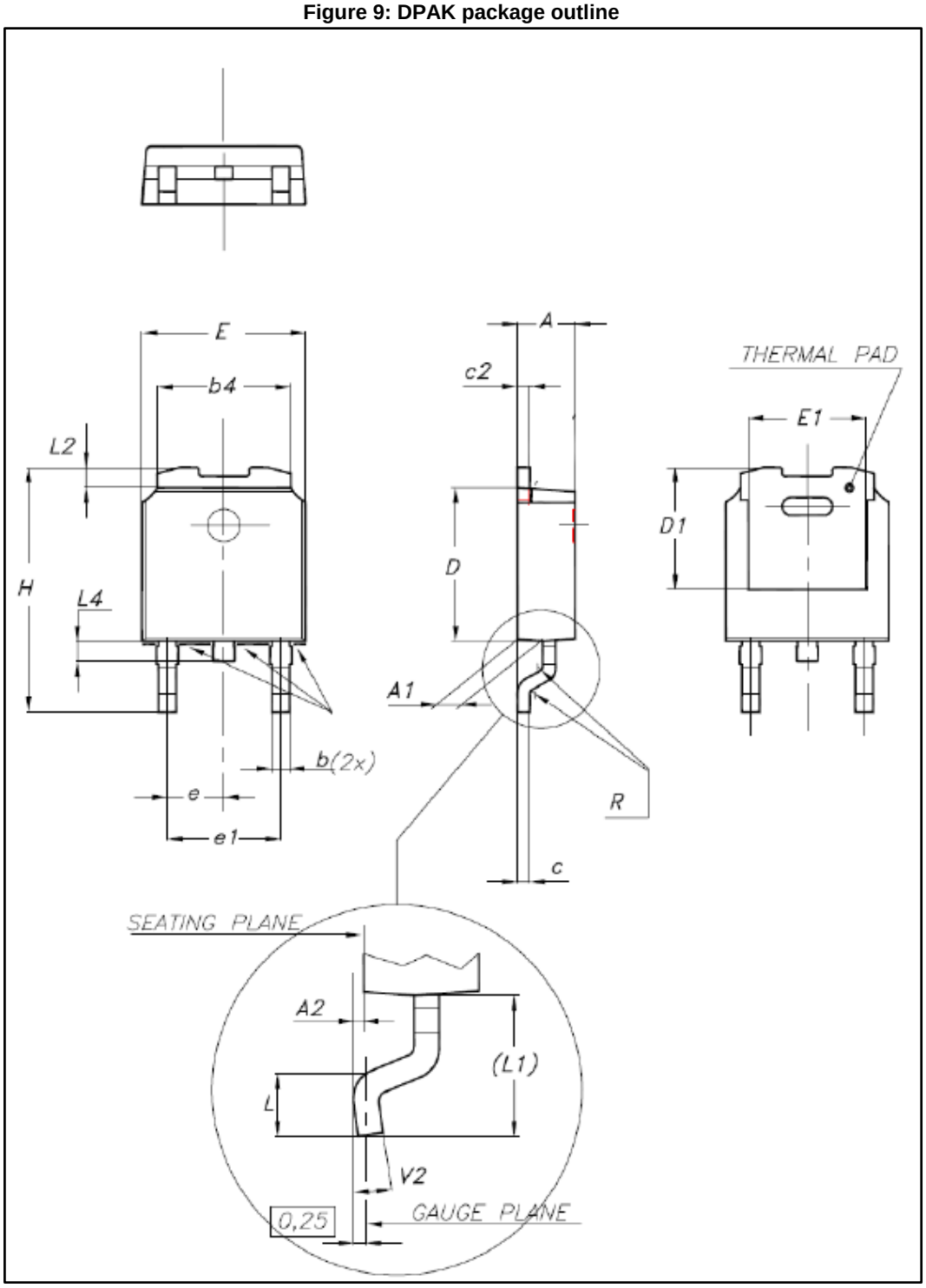
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0

2.1 DPAK package information

Figure 9: DPAK package outline

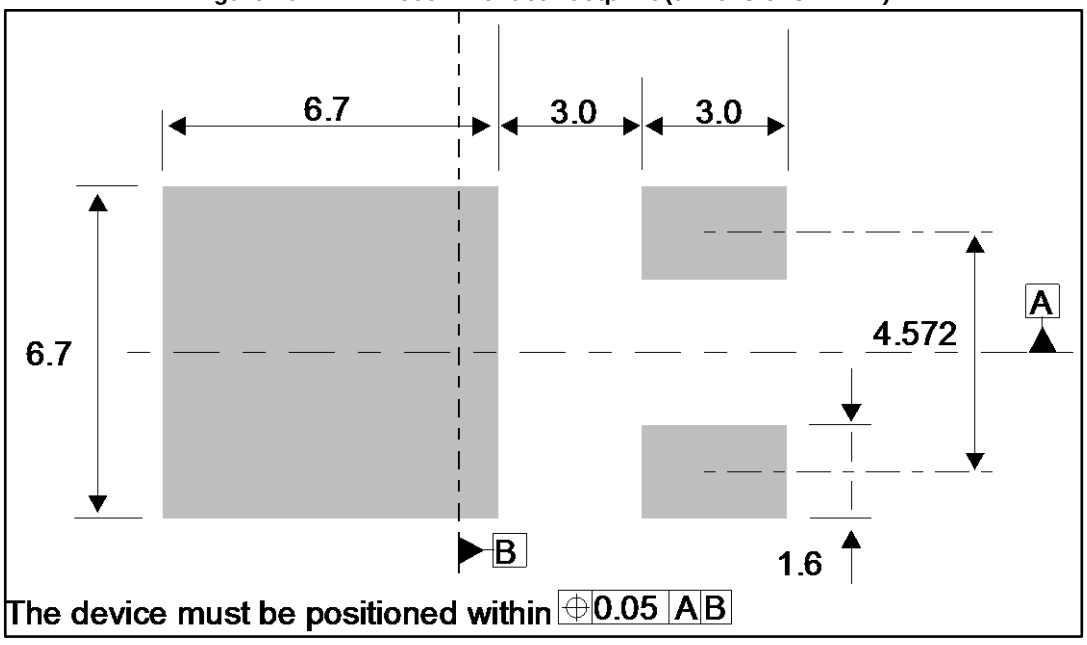


This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5: DPAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.18	2.40	0.085	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
b	0.64	0.90	0.025	0.035
b4	4.95	5.46	0.194	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	4.95	5.60	0.194	0.220
E	6.35	6.73	0.250	0.265
E1	4.32	5.50	0.170	0.216
e	2.286 typ.		0.090 typ.	
e1	4.40	4.70	0.173	0.185
H	9.35	10.40	0.368	0.409
L	1.0	1.78	0.039	0.070
L2		1.27		0.050
L4	0.60	1.02	0.023	0.040
V2	-8°	+8°	-8°	+8°

Figure 10: DPAK recommended footprint (dimensions in mm)



3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS8L30B-TR	LS 30	DPAK	0.32 g	2500	Tape and reel

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
Jul-2002	2A	First issue
16-Apr-2005	3	IPAK package Added.
01-Mar-2006	4	IPAK connector identifiers corrected on page 1. ECOPACK statement added. Document reformatted to current standard.
18-Oct-2016	5	Updated DPAK package information and reformatted to current standard. Removed IPAK package.

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